

Global Flip Chip Bonder Market by Size, by Type, by Application, by Region, History and Forecast 2019-2030

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Abstracts

Flip chip is a method used for components or devices that can be bonded directly onto a substrate, board or carrier face-down. The connection is made through conductive bumps placed on the surface of the die. The placing process amounts to the following:

1. Die is picked up and place on a 'flipping device'
2. Die is 'flipped' and moved to hover over the substrate (or board or carrier) where bumps reside - precisely positioned in their previously defined positions
3. The tool then places the die on the bump with a programmed amount of force

Flip chip bumping is a vital step to the process. The bump provides the necessary electrical connection between the die and the substrate, provides thermal conduction through the two materials, acts as a 'spacer' to prevent electrical shorts and provides mechanical support.

Flip chips avoid wire bonding and therefore are able to be much smaller than their counterparts. Flip chip processes have been around for more than 40 years. Since then, thousands of applications have taken advantage of the size and cost benefits enabled by the flip chip assembly method.

According to APO Research, The global Flip Chip Bonder market is projected to grow from US\$ million in 2024 to US\$ million by 2030, at a Compound Annual Growth Rate (CAGR) of % during the forecast period.

Global Flip Chip Bonder key players include Besi, ASM Pacific Technology, Shibaura, Kulicke & Soffa, etc. Global top four manufacturers hold a share nearly 70%.

China is the largest market, with a share about 25%, followed by United States, and Taiwan, both have a share about 30 percent.

In terms of product, Fully Automatic is the largest segment, with a share over 75%. And in terms of application, the largest application is IDMs, followed by OSAT.

In terms of production side, this report researches the Flip Chip Bonder production, growth rate, market share by manufacturers and by region (region level and country level), from 2019 to 2024, and forecast to 2030.

In terms of consumption side, this report focuses on the sales of Flip Chip Bonder by region (region level and country level), by company, by type and by application. from 2019 to 2024 and forecast to 2030.

This report presents an overview of global market for Flip Chip Bonder, capacity, output, revenue and price. Analyses of the global market trends, with historic market revenue or sales data for 2019 - 2023, estimates for 2024, and projections of CAGR through 2030.

This report researches the key producers of Flip Chip Bonder, also provides the consumption of main regions and countries. Of the upcoming market potential for Flip Chip Bonder, and key regions or countries of focus to forecast this market into various segments and sub-segments. Country specific data and market value analysis for the U.S., Canada, Mexico, Brazil, China, Japan, South Korea, Southeast Asia, India, Germany, the U.K., Italy, Middle East, Africa, and Other Countries.

This report focuses on the Flip Chip Bonder sales, revenue, market share and industry ranking of main manufacturers, data from 2019 to 2024. Identification of the major stakeholders in the global Flip Chip Bonder market, and analysis of their competitive landscape and market positioning based on recent developments and segmental revenues. This report will help stakeholders to understand the competitive landscape and gain more insights and position their businesses and market strategies in a better way.

This report analyzes the segments data by type and by application, sales, revenue, and price, from 2019 to 2030. Evaluation and forecast the market size for Flip Chip Bonder sales, projected growth trends, production technology, application and end-user

industry.

Descriptive company profiles of the major global players, including BESI, ASMPT, Shibaura, Muehlbauer, K&S, Hamni, AMICRA Microtechnologies, SET and Athlete FA, etc.

Flip Chip Bonder segment by Company

BESI

ASMPT

Shibaura

Muehlbauer

K&S

Hamni

AMICRA Microtechnologies

SET

Athlete FA

Flip Chip Bonder segment by Type

Fully Automatic

Semi-Automatic

Flip Chip Bonder segment by Application

IDMs

OSAT

Flip Chip Bonder segment by Region

North America

U.S.

Canada

Europe

Germany

France

U.K.

Italy

Russia

Asia-Pacific

China

Japan

South Korea

India

Australia

China Taiwan

Indonesia

Thailand

Malaysia

Latin America

Mexico

Brazil

Argentina

Middle East & Africa

Turkey

Saudi Arabia

UAE

Study Objectives

1. To analyze and research the global status and future forecast, involving, production, value, consumption, growth rate (CAGR), market share, historical and forecast.
2. To present the key manufacturers, capacity, production, revenue, market share, and Recent Developments.
3. To split the breakdown data by regions, type, manufacturers, and Application.
4. To analyze the global and key regions market potential and advantage, opportunity and challenge, restraints, and risks.
5. To identify significant trends, drivers, influence factors in global and regions.
6. To analyze competitive developments such as expansions, agreements, new product launches, and acquisitions in the market.

Reasons to Buy This Report

1. This report will help the readers to understand the competition within the industries and strategies for the competitive environment to enhance the potential profit. The report also focuses on the competitive landscape of the global Flip Chip Bonder market, and introduces in detail the market share, industry ranking, competitor ecosystem, market performance, new product development, operation situation, expansion, and acquisition. etc. of the main players, which helps the readers to identify the main competitors and deeply understand the competition pattern of the market.
2. This report will help stakeholders to understand the global industry status and trends of Flip Chip Bonder and provides them with information on key market drivers, restraints, challenges, and opportunities.
3. This report will help stakeholders to understand competitors better and gain more insights to strengthen their position in their businesses. The competitive landscape section includes the market share and rank (in volume and value), competitor ecosystem, new product development, expansion, and acquisition.
4. This report stays updated with novel technology integration, features, and the latest developments in the market.
5. This report helps stakeholders to gain insights into which regions to target globally.
6. This report helps stakeholders to gain insights into the end-user perception concerning the adoption of Flip Chip Bonder.
7. This report helps stakeholders to identify some of the key players in the market and understand their valuable contribution.

Chapter Outline

Chapter 1: Provides an overview of the Flip Chip Bonder market, including product definition, global market growth prospects, production value, capacity, and average price forecasts (2019-2030).

Chapter 2: Analysis key trends, drivers, challenges, and opportunities within the global Flip Chip Bonder industry.

Chapter 3: Detailed analysis of Flip Chip Bonder market competition landscape.

Including Flip Chip Bonder manufacturers' output value, output and average price from 2019 to 2024, as well as competition analysis indicators such as origin, product type, application, merger and acquisition information, etc.

Chapter 4: Provides the analysis of various market segments by type, covering the market size and development potential of each market segment, to help readers find the blue ocean market in different market segments.

Chapter 5: Provides the analysis of various market segments by application, covering the market size and development potential of each market segment, to help readers find the blue ocean market in different downstream markets.

Chapter 6: Provides profiles of key players, introducing the basic situation of the main companies in the market in detail, including product production/output, value, price, gross margin, product introduction, recent development, etc.

Chapter 7: Production/Production Value of Flip Chip Bonder by region. It provides a quantitative analysis of the market size and development potential of each region in the next six years.

Chapter 8: Consumption of Flip Chip Bonder in regional level and country level. It provides a quantitative analysis of the market size and development potential of each region and its main countries and introduces the market development, future development prospects, market space, and production of each country in the world.

Chapter 9: Analysis of industrial chain, including the upstream and downstream of the industry.

Chapter 10: Concluding Insights of the report.

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